

-30V P-Channel Enhancement Mode MOSFET

Description

The AP7P03MI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

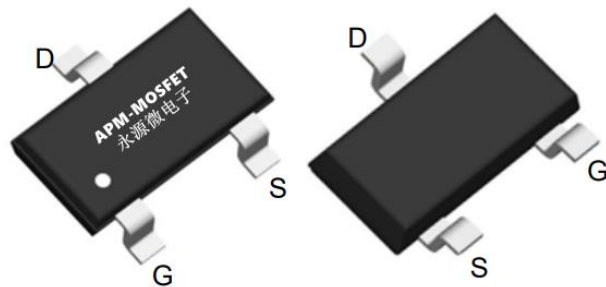
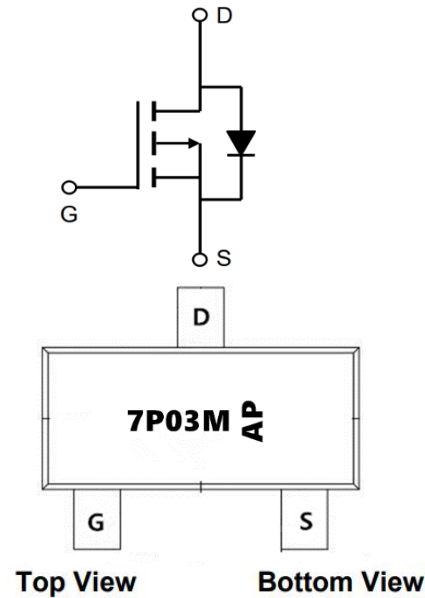
$V_{DS} = -30V$ $I_D = 7.0A$

$R_{DS(ON)} < 32m\Omega$ @ $V_{GS}=10V$ (Type: 26m Ω)

Application

Boost driver

Brushless motor



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP7P03MI	SOT23-3L	7P03M AP	3000

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-7.0	A
I _D @T _C =70°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-4.5	A
IDM	Pulsed Drain Current ²	-28	A
P _D @T _C =25°C	Total Power Dissipation ³	1.8	W
TSTG	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C
R _{θJA}	Thermal Resistance Junction-Ambient ¹	125	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	110	°C/W

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Electrical Characteristics (T_c=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30	-33	---	V
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-7A	---	25	32	mΩ
		V _{GS} =-4.5V, I _D =-5A	---	33	45	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0	-1.5	-2.5	V
IDSS	Drain-Source Leakage Current	V _{DS} =-24V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =-5V, I _D =-7A	---	15	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz		15	30	Ω
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-20V, V _{GS} =-4.5V, I _D =-7A	---	9.8	---	nC
Q _{gs}	Gate-Source Charge		---	2.2	---	
Q _{gd}	Gate-Drain Charge		---	3.4	---	
Td(on)	Turn-On Delay Time	V _{DD} =-15V V _{GS} =-10V R _G =3.3Ω I _D =-5A	---	16.4	---	ns
T _r	Rise Time		---	20.2	---	
Td(off)	Turn-Off Delay Time		---	55	---	
T _f	Fall Time		---	10	---	
Ciss	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	930	---	pF
Coss	Output Capacitance		---	148	---	
Crss	Reverse Transfer Capacitance		---	115	---	
IS	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	-8	A
VSD	Diode Forward Voltage ²	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1.2	V

Note :

- 1、 The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

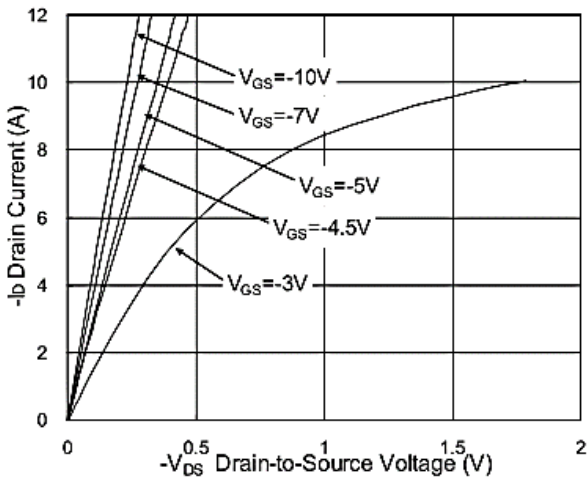


Fig.1 Typical Output Characteristics

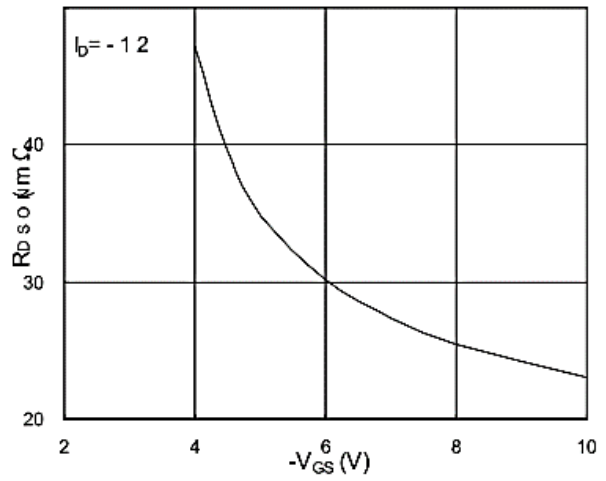


Fig.2 On-Resistance v.s Gate-Source

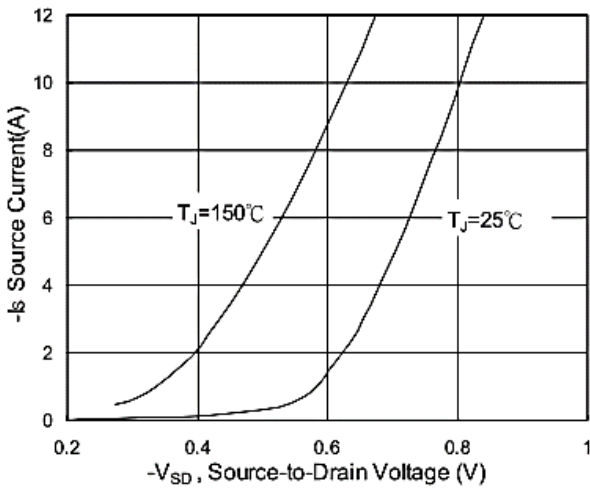


Fig.3 Forward Characteristics Of Reverse

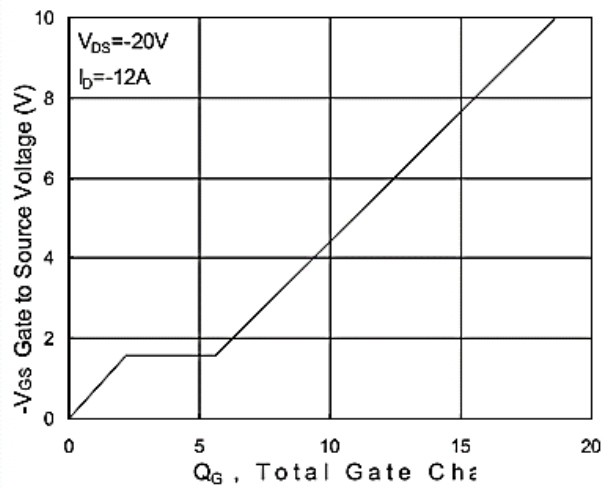


Fig.4 Gate-Charge Characteristics

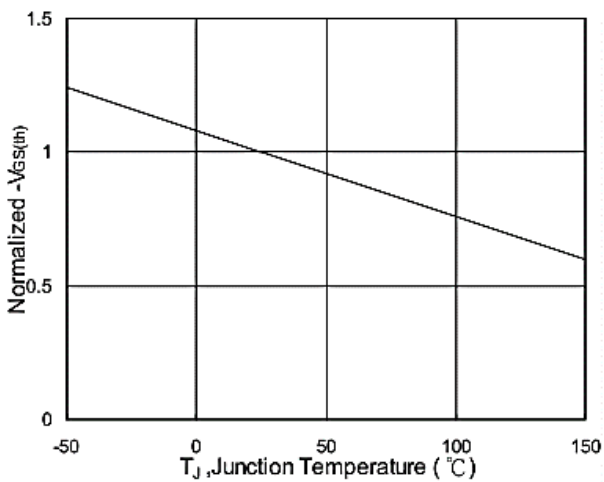


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

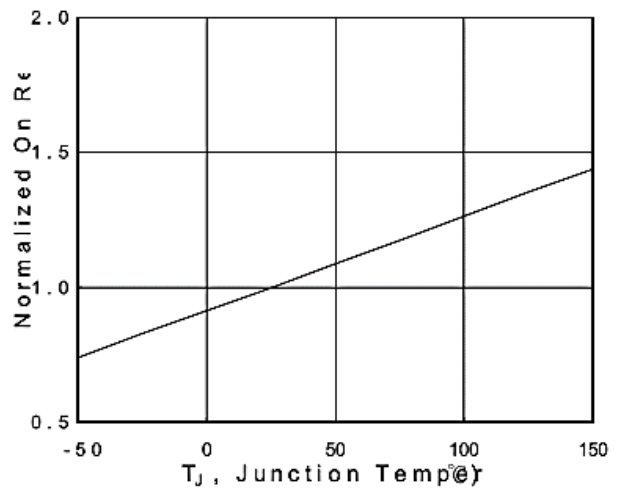


Fig.6 Normalized $R_{DS(on)}$ v.s T_J



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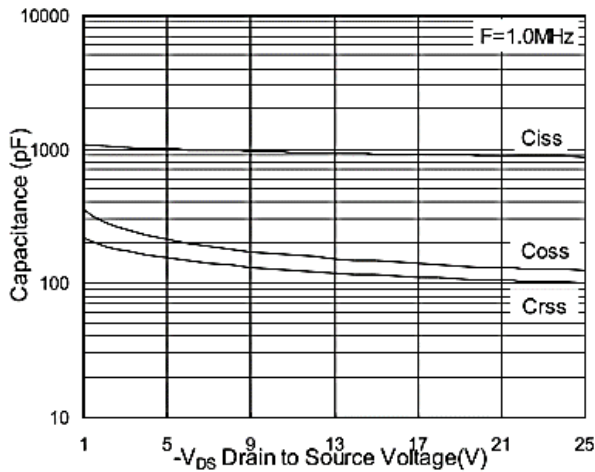


Fig.7 Capacitance

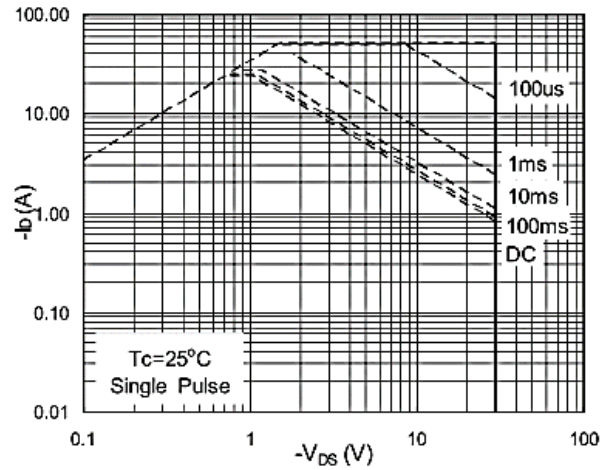


Fig.8 Safe Operating Area

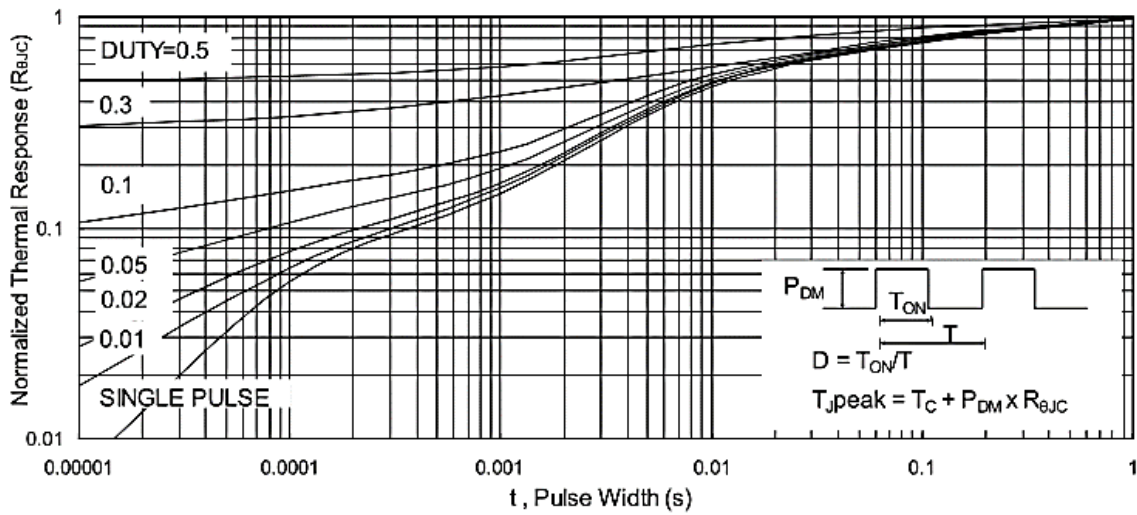


Fig.9 Normalized Maximum Transient Thermal Impedance

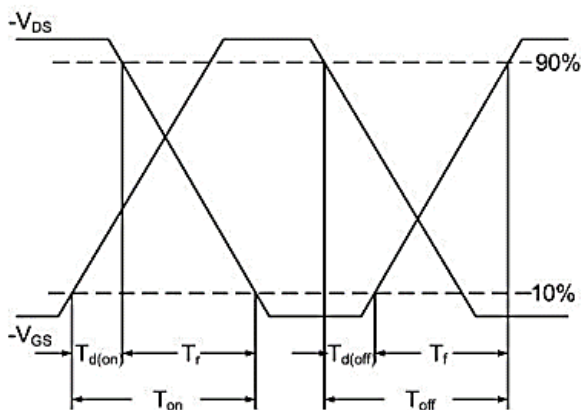


Fig.10 Switching Time Waveform

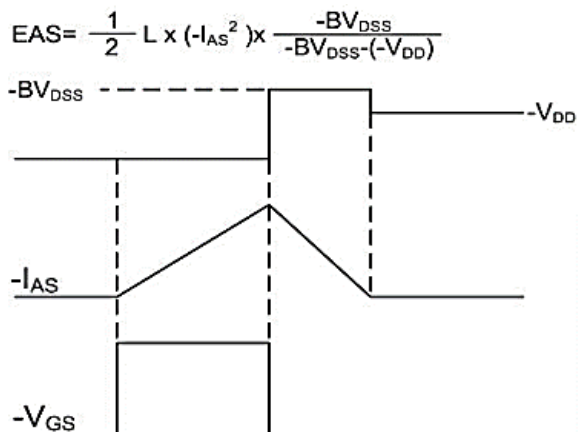
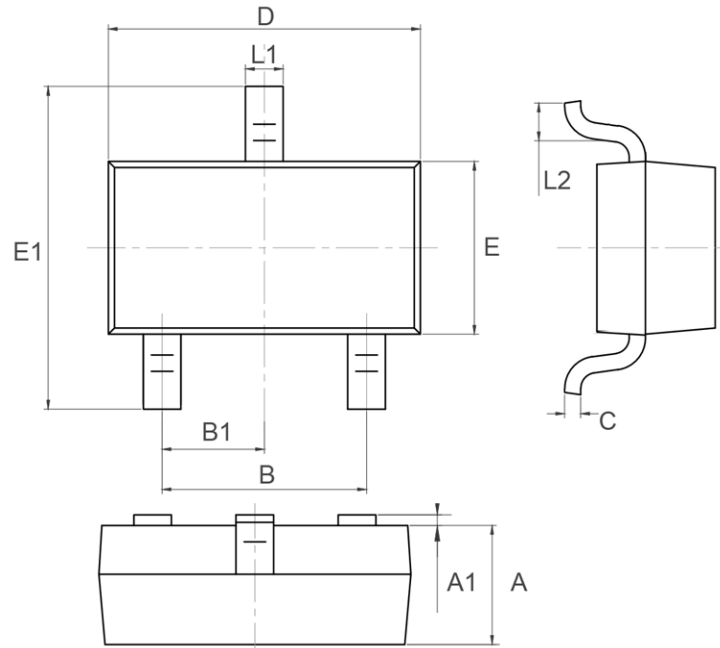


Fig.11 Unclamped Inductive Waveform

Package Mechanical Data-SOT23-3L-Single



Symbol	Dim in mm		
	Min	Typ	Max
A	1	1.1	1.2
A1	0	0.05	0.1
B	1.8	1.9	2
B1	0.95TYP		
C	0.1	0.15	0.2
D	2.82	2.92	3.02
E	1.5	1.6	1.7
E1	2.65	2.8	2.95
L1	0.3	0.4	0.5
L2	0.3	0.45	0.6

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Edition	Date	Change
REV1.0	2023/12/30	Initial release

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